

# **ESSCIRC 2023- IEEE 49th European Solid State Circuits Conference (ESSCIRC 2023)**

**Lisbon, Portugal  
11-14 September 2023**



**IEEE Catalog Number: CFP23542-POD  
ISBN: 979-8-3503-0421-3**

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IEEE Catalog Number:	CFP23542-POD
ISBN (Print-On-Demand):	979-8-3503-0421-3
ISBN (Online):	979-8-3503-0420-6
ISSN:	1930-8833

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José Epifânio Da Franca

*Universidade de Lisboa, Portugal*

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*Massachusetts Institute of Technology, United States*

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<sup>1</sup>State Key Laboratory of ASIC and System, Fudan University, China;

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<sup>1</sup>University of Southern California, United States; <sup>2</sup>University of Waterloo, Canada

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**Date:** Wednesday, September 13, 2023  
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**Date:** Wednesday, September 13, 2023  
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**Room:** Room 5.B

**Chair(s):** Dmytro Cherniak, *Infineon Technologies*  
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<sup>1</sup>*Institute of Semiconductors, Chinese Academy of Sciences, China;*

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**Date:** Wednesday, September 13, 2023

**Room:** Room 5.A

**Chair(s):** Tom Van Breusegem, *ICSense*  
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<sup>1</sup>National Yang Ming Chiao Tung University, Taiwan; <sup>2</sup>Chip-GaN Power Semiconductor Corporation, Taiwan; <sup>3</sup>Realtek Semiconductor Corp, Taiwan

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<sup>1</sup>Osaka University, Japan; <sup>2</sup>National Yang Ming Chiao Tung University, Taiwan

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**Date:** Thursday, September 14, 2023

**Room:** Audit. I

**Chair(s):** José de La Rosa, *IMSE-CNM, Universidad de Sevilla*

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*Universidad de Sevilla, Spain*

## Innovations in High-Speed A/D Converters

**Date:** Thursday, September 14, 2023

**Room:** Audit. II

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<sup>3</sup>East China Normal University, China

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**Date:** Thursday, September 14, 2023

**Room:** Audit. III

**Chair(s):** Alexander Fish, *Bar Ilan University*  
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<sup>1</sup>Southern University of Science and Technology, China; <sup>2</sup>Hong Kong University of Science and Technology, China; <sup>3</sup>AI Chip Center for Emerging Smart System, Hong Kong

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**Room:** Audit. IV

**Chair(s):** Paul Walsh, *Infineon Technologies*  
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<sup>1</sup>*National Yang Ming Chiao Tung University, Taiwan;* <sup>2</sup>*National Taiwan University, Taiwan*

## VCSEL Transmitters

**Date:** Thursday, September 14, 2023

**Room:** Room 5.A

**Chair(s):** Filip Tavernier, *KU Leuven*  
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<sup>1</sup>*Technische Universität Berlin, Germany*; <sup>2</sup>*VI Systems GmbH, Germany*

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<sup>1</sup>*Hong Kong University of Science and Technology, Hong Kong*;

<sup>2</sup>*Southern University of Science and Technology, China*

## Advanced CMOS LNA Techniques

**Date:** Thursday, September 14, 2023

**Room:** Room 5.B

**Chair(s):** Eric Klumperink, *University of Twente*  
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**Date:** Thursday, September 14, 2023

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**Chair(s):** Mattias Palm, *Ericsson*  
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## A-SSCC Special Session

**Date:** Thursday, September 14, 2023

**Room:** Audit. III

**Chair(s):** Andreia Cathelin, *STMicroelectronics*  
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<sup>1</sup>*Korea Advanced Institute of Science and Technology, Korea;*

<sup>2</sup>*New York University Abu Dhabi, U.A.E.*

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Wang Ye, Linfang Wang, Zhidao Zhou, Junjie An, Weizeng Li, Hanghang Gao, Xiaoxin Xu, Jinshan Yue, Jianguo Yang, Dashan Shang, Chunmeng Dou, Qi Liu, Ming Liu

*Institute of Microelectronics of the Chinese Academy of Sciences, China*

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<sup>1</sup>*National Yang Ming Chiao Tung University, Taiwan;* <sup>2</sup>*Realtek Semiconductor Corp, Taiwan*

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<sup>1</sup>*Amicro Semiconductor Co. Ltd, China;* <sup>2</sup>*Shanghai Jiao Tong University, China;*

<sup>3</sup>*University of Macau, Macau*

## SRAM Digital Computing in Memory

**Date:** Thursday, September 14, 2023

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<sup>1</sup>Columbia University, United States; <sup>2</sup>Intel Corporation, United States

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**Date:** Thursday, September 14, 2023  
**Room:** Room 5.A  
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<sup>1</sup>Leibniz Universität Hannover, Germany; <sup>2</sup>Infineon Technologies Austria AG, Austria

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<sup>1</sup>National Yang Ming Chiao Tung University, Taiwan; <sup>2</sup>Chip-GaN Power Semiconductor Corporation, Taiwan; <sup>3</sup>Realtek Semiconductor Corp, Taiwan

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<sup>1</sup>Politecnico di Milano, Italy; <sup>2</sup>STMicroelectronics, Italy

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<sup>1</sup>Columbia University, United States; <sup>2</sup>Intel Corporation, United States; <sup>3</sup>Texas Instruments, United States; <sup>4</sup>IBM Research, United States

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**Date:** Thursday, September 14, 2023

**Room:** Audit. I

**Chair(s):** Nuno Paulino, *Universidade NOVA de Lisboa*

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**Room:** Audit. III

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<sup>1</sup>Stanford University, United States; <sup>2</sup>Taiwan Semiconductor Manufacturing Company Limited, Taiwan

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**Chair(s):** Georgi Radulov, *TU Eindhoven*  
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**Date:** Thursday, September 14, 2023  
**Room:** Room 5.A  
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